



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

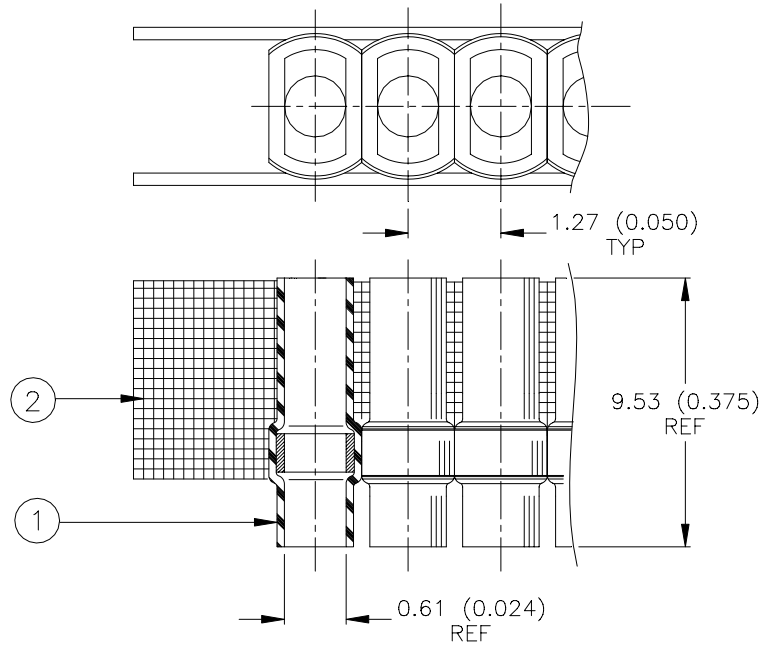
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SPECIFICATION CONTROL DRAWING



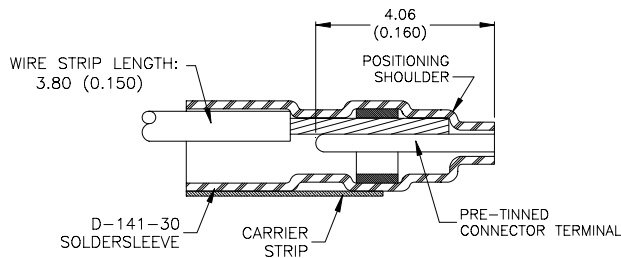
MATERIALS

1. SOLDERSLLEEVE: D-141-30. Quantity Per Assembly: 1000
2. CARRIER STRIPS: Adhesive Coated High Temperature Tape

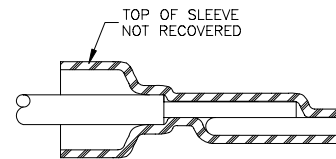
APPLICATION

1. This assembly is designed to terminate a single 26, 28, or 30 AWG PVC insulated wire to micro-miniature connectors with terminals on 1.27 (0.050) center spacing.
2. Sleeves are to be installed using Raychem-approved convection or infrared heating tools.
3. Strip wires to 3.81 (0.150).
4. Trim connector terminals, if required to 4.06 (0.160) and pre-tin.
5. Heat should be applied until the solder perform melts and flows. The insulation sleeve will partially recover down onto the wire insulation sleeve near the solder joint. The tops of the sleeves should not recover onto wire insulation. Enough heat has been applied when the solder perform has completely lost its original shape on all sides of the termination and a fillet of solder is formed between conductor and terminal.

SolderSleeve and Lead in
Position for Assembly



Terminated Assembly



tyco <i>Electronics</i>	Raychem	Tyco Electronics Corporation 300 Constitutional Drive Menlo Park, CA 94025 USA	TITLE: SOLDERPAK ASSEMBLY, MICRO-MINIATURE CONNECTOR 1.27 (0.100) Center Spacing					
Unless otherwise specified dimensions are in millimeters. Inches dimensions are in between brackets.			DOCUMENT NO.: D-713-03					
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.	DATE: 25-Jun-01	DOC ISSUE: 1				
DRAWN BY: M. FORONDA	CAGE CODE: 06090	REPLACES: N/A	DCR NUMBER: D001338	PROD. REV.: A	SCALE: None	SIZE: A	SHEET: 1 of 1	

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